

ST60 Edge-Card Linear Antennas - Layout

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Layout Considerations for ST60 Antennas

Project: GENERIC PCB (FR4, 4 Layers, Development PCB) Customer: GENERIC

Reference documents:

Document Name	Document Type	Description / Comments	
R380.845.002A EN.pdf	T.D.S.	H-Polarization Gold Plated LCP Horn Antenna / Commercial Range	
R380.845.102A EN.pdf	T.D.S.	V-Polarization Gold Plated LCP Horn Antenna / Commercial Range	
R380.846.002A EN.pdf	T.D.S.	H-Polarization Gold Plated LCP Horn Antenna / Industrial Range	
R380.846.102A EN.pdf	T.D.S.	V-Polarization Gold Plated LCP Horn Antenna / Industrial Range	
201910575-10-0_24-10-19A.DXF.zip	DXF Files	H-Polarization Horn Antenna Footprint	
201910575-10-1_24-10-19A.DXF.zip	DXF Files	V-Polarization Horn Antenna Footprint	

Content:

This document is intended as a reference for the layout design when using the Stackup shown in table 1.

Please note that the transition from the PCB to the antenna is performance critical. Any modification to the PCB stackup and / or board layout may result in RF performance degradation, and therefore should be assessed.

The ST60 chips and antennas are mm-wave devices. General microwave design rules should be applied to design the complete board (and the areas comprising the ST60 chips and antenna in particular) in order to avoid crosstalk and resonance phenomenons. Particular attention shall be paid to plated through hole locations, line characteristic impedance, and sharp discontinuities.

In the following layout antennas are placed on the top layer

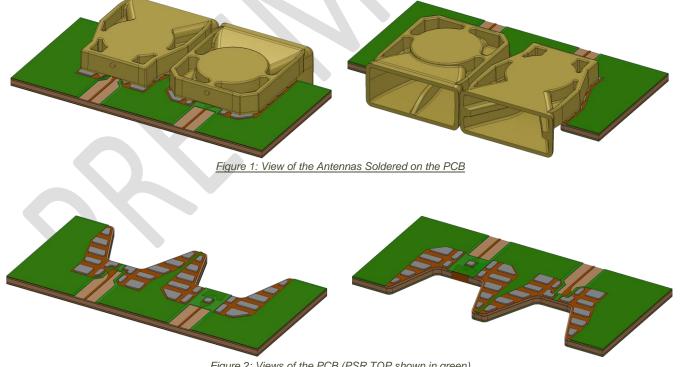


Figure 2: Views of the PCB (PSR TOP shown in green)



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Associated PCB Stackup:

The PCB is a 4 copper layers stackup, 0.63mm thick with plated thru holes.

	Material (For information Only)	Er (1)	Tan∆	Thickness (µm) (2)	
ENIG plating				4	
Solder mask	Probimer 77	4 @ TBD		20	
Copper 1				35	
Core	IT 158	4.1 @ 5GHz	0.018 @ 5GHz	70 (3)	
Copper 2				18	
Prepreg	IT 158	4.1 @ 5GHz	0.018 @ 5GHz	319	
Copper 3				18	
Core	IT 158	4.1 @ 5GHz	0.018 @ 5GHz	70 (3)	
Copper 4				35	
Solder mask	Probimer 77	4 @ TBD		20	
ENIG plating				4	
(1): Dielectric Constant Tolerance: ±10%					

(2): Thickness Tolerance: ±10%

(3): Works with 81µ Nominal Thickness Cores

Table 1: PCB Stackup

PCB characteristics

Copper:

Min track width / spacing: 0.12mm

Tolerance: +/- 40um

Vias:

Plated Thru Holes 0 Drill diameter: 0.2mm

Pad diameter: 0.45mm (inner and outer layers)

Plugged vias (to control the quantity of solder paste on the pads surface)

Via stitching: 0.5mm pitch typ. (0.7mm max)

Surface finish: ENIG plating without solder mask is suggested on the transmission lines to minimize losses between chips and antennas.

The antennas are 1 port component (pad location is indicated below, p. 5 and 8). The pad is where the track coming from the chip will be

If required by your PCB design tool, you might need to add 1 port for each ground via (in the pads) so they are part of the component footprint.

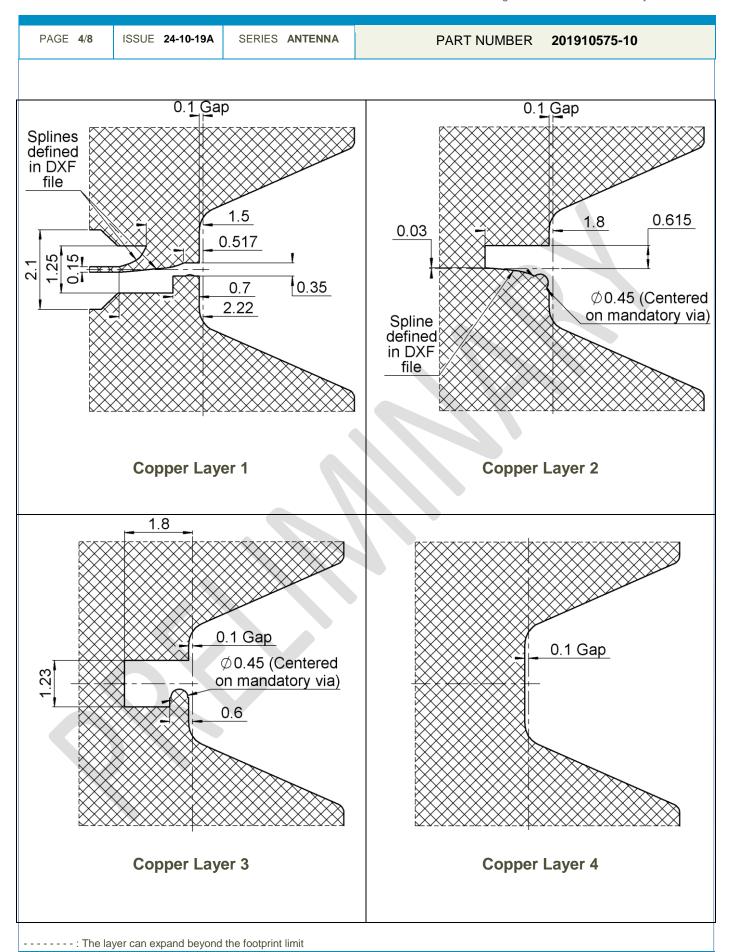


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PAGE 3/8 ISSUE 24-10-19A SERIES ANTENNA PART NUMBER 201910575-10 **H-Polarization Horn Antenna:** 2.7 2x R0.35 2.25 2.1 / Flat 1.25 2x R0.5 .5 min. ညိ ညိ S Origin of DXF Files αi 0.35 0.2 0.8 Edge of PCB (w.Contour Shadowed) Contour **PSR TOP** Photo Solder Resist openings are shown here. These are the areas where there is no PSR. 2 rows of vias, @ 0,5 Typ. pitch, placed as defined (for at least 1 hole), or as close as possible to the edges of the copper layers. 0 0 0 0 0 00000 365 0.35 Mandatory Via 0000 00000 Drill: \emptyset 0.2 Plugged Vias 0 (w. Contour Shadowed) (No Opening) VIAS PSR BOTTOM The via marked as "mandatory" shall not be suppressed or moved. In the antenna area, bottom is fully covered by PSR. For the other vias, we recommend a 0.5mm pitch stitching on two rows ----: The layer can expand beyond the footprint limit

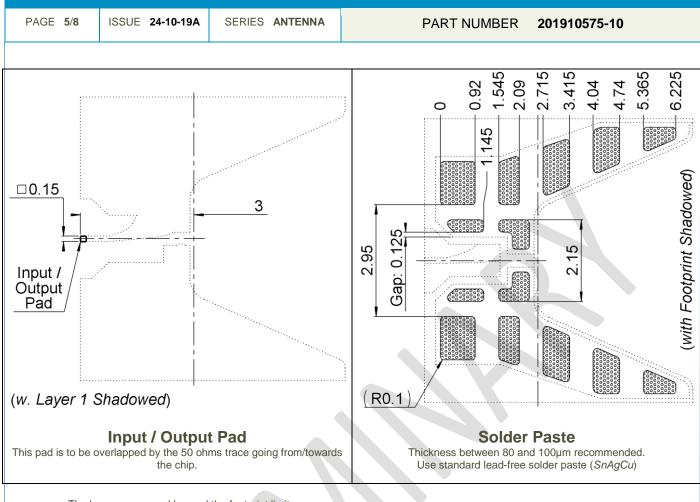


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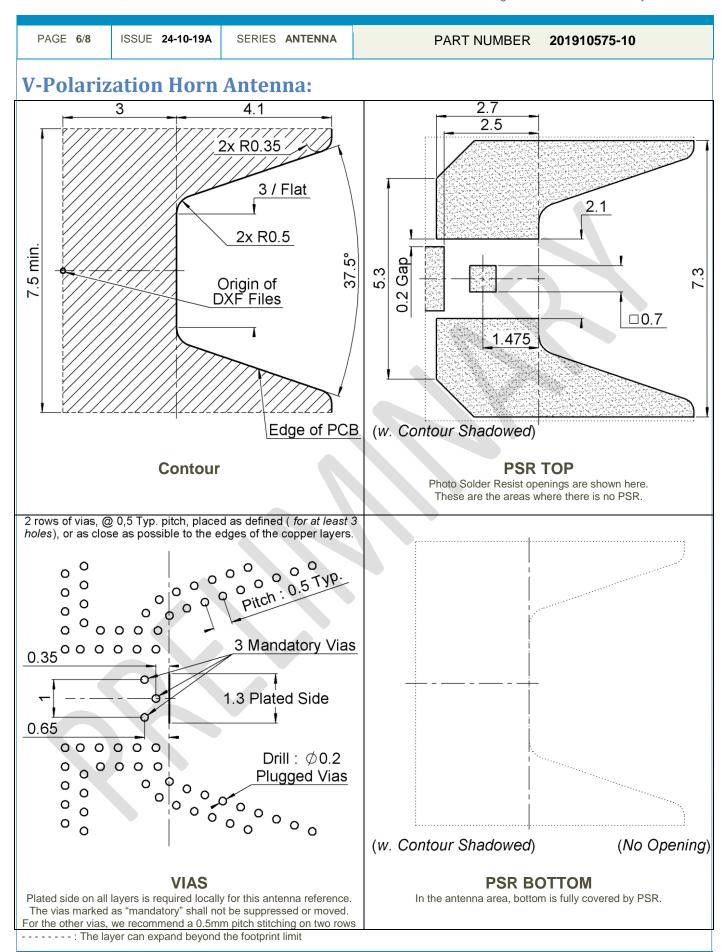
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----: The layer can expand beyond the footprint limit

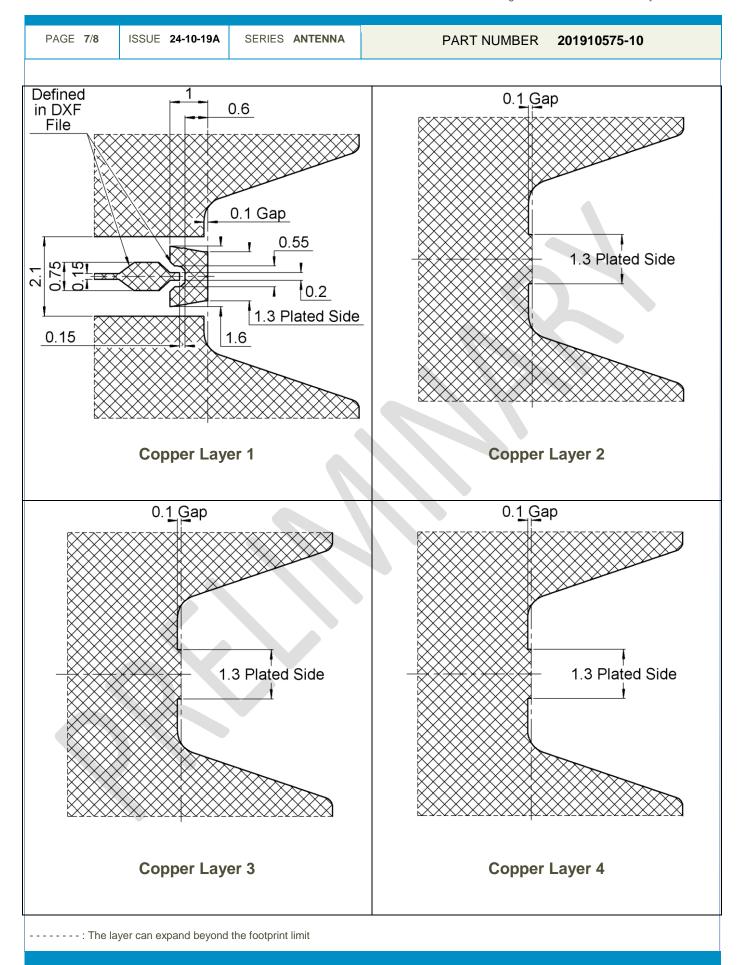


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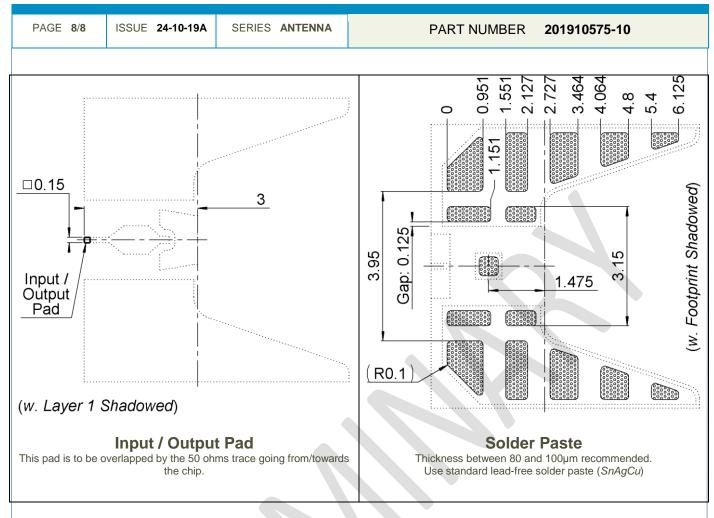


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----: The layer can expand beyond the footprint limit

See TDS for reflow instructions and temperature profile.
See attached DXF files (*R12 version*) for exact dimensions and vias position.